



Product Change Notification

Date: Monday, February 28, 2011

PCN#: 140A00197

Subject: Replace Military with Extended temperature conditions

Dear Customer,

In an effort to better communicate to you, our user community, we have implemented a e-mail version for our PCN process in addition to our PCN website. While you may receive a notification from us concerning a particular part or part numbers, it is not an indication that you use or have ordered these particular parts, but merely a communication to notify our user community as a whole. Please review your sales orders, POs, records, etc. to determine if this particular PCN impacts your activities or affects your business.

Microsemi Power and Microelectronics Group wishes to inform you of operational condition changes to all package versions of the following products:

WMF2M8-xxx5, WF2M16-xxx5, WF2M32-xxx5, WF4M32-xxx5

The current flash die is going EOL and will be purchased as a last time buy. After depletion of inventory the new die AM29F016D will be used but the Military (M) grade product and Compliant (Q) product will no longer be available. Military product will be replaced with extended temperature product and Compliant product will be replaced with extended compliant product. Extended temperature condition devices are fully operational from -55C to 100C. Operation above 100C to 125C is limited to read only operations. These changes have been implemented due to functional write/erase problems identified above 100°C on the new die.

Microsemi Power and Microelectronics Group will continue to support the existing military and compliant product until the depletion of the old die revision. Product based on the old die revision will be sold on a "first come first serve" basis. Contact the factory for availability.

As technology moves at a much faster pace, advanced embedded electronic components play a more strategic role. Constant changes and advancements in technology mandate that we anticipate changes and directions in technology for the benefit of our customers. As one of the pioneers in advanced semiconductor packaging and high-density memory solutions, we stand ready to assist you in managing this evolution of technology. If we can provide any additional assistance, please contact us at 602.437.1520 or complete a contact form at www.whiteedc.com/contact_us.html.

Best regards,
Microsemi Power and Microelectronics Engineering Group